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Nakano et al.

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(54) **PLASMA TREATMENT EQUIPMENT**

(56)

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(58) **Field of Search** **118/723 E, 723 ER, 118/723 R, 728, 723 MW, 723 MA, 723 ME, 723 MR, 723 I, 723 IR, 723 AN; 156/345**

(57)

ABSTRACT

The invention provides a plasma equipment which is advantageous in that the susceptor impedance is small, the dependence on the frequency is low, the power consumption efficiency is high, the film forming speed is faster as compared with conventional plasma equipment, and the film quality is high. Metal plates AC short between a chamber wall and a shield of an electrode of the same DC potential as the chamber.

12 Claims, 20 Drawing Sheets

